PMP10074 Rev_A BOM						
Count	RefDes	Value	Description	Size	Part Number	MFR
1	C6	0.047uF	Capacitor, Ceramic, 0.047uF, 50-V, X7R, 20%	603	Std	Std
1	C8	0.1uF	Capacitor, Ceramic, 0.1-uF, 50-V, X7R, 20%	603	Std	Std
1	C14	0.47uF	Capacitor, Ceramic, 0.01-uF, 50-V, X7R, 20%	603	Std	Std
1	C13	220pF	Capacitor, Ceramic, 220-pF, 50-V, COG, 10%	603	Std	Std
1	C7	150pF	Capacitor, Ceramic, 150-pF, 50-V, X7R, 20%	603	Std	Std
1	C5	470pF	Capacitor, Ceramic, 470-pF, 50-V, X7R, 20%	603	Std	Std
1	C102	470pF	Capacitor, Ceramic, 470pF, 50-V, X7R, 20%	603	Std	Std
1	C2	68 pF	Capacitor, Ceramic, 50V, X7R, 20%	603	Std	Std
1	C3	.22uF	Capacitor, Ceramic, 50V, X7R, 20%	805	Std	Std
1	C4	.22uF	Capacitor, 40V, X7R, 20%	805	Std	Std
2	C11-12	10uF	Capacitor, Ceramic X7R, 16V, ±10%	1206	C3216X7R1C106K	TDK
1	C100	4.7uF	Capacitor, Ceramic X7R, 16V, ±10%	1206	C3216X7R1C475K	TDK
2	C9-10	DNP	DNP	0.260 x 0.276 inch	DNP	N/A
1	C1	100uF	Capacitor, Aluminum, 100-μF, 63-V, 20%	0.457 x 0.406	EEVFK1J101P	Panasonic
1	C101	47uF	Capacitor, Aluminum, vvV, ±20%	0.328 x 0.328 inch	EEEFK1H470P	Panasonic
1	D1	NRVBS360T3G	Diode, Automotive Schottky, 3A, 60V	SMC	NRVBS360T3G	On Semi
2	L2 L100	100uH	Inductor, SMT, 100-uH, 2.1-A, 0.19-ohm	0.492" sq	CLF12555T-101M-D	TDK
1	R4	0	Resistor, Chip, 0-Ohms, 1/16-W, 1%	603	Std	Std
1	R3	1.0K	Resistor, Chip, 1.0K-Ohms, 1/16-W, 1%	603	Std	Std
1	R7	100K	Resistor, Chip, 100K-Ohms, 1/16-W, 1%	603	Std	Std
1	R5	10K	Resistor, Chip, 10K-Ohms, 1/16-W, 1%	603	Std	Std
1	R6	25.5	Resistor, Chip, 25.5-Ohms, 1/16-W, 1%	603	Std	Std
1	R8	49.9	Resistor, Chip, 49.9-Ohms, 1/16-W, 1%	603	Std	Std
2	R9 R101	6.81K	Resistor, Chip, 6.81K-Ohms, 1/16-W, 1%	603	Std	Std
1	R1	91K	Resistor, Chip, 91K-Ohms, 1/16-W, 1%	603	Std	Std
1	R2	0.039	Resistor, Chip, 0.039-Ohms, 1/2-W, 5%	2010	Std	Std
1	R100	6.8	Resistor, Chip, 6.8-Ohms, 1/2-W, 5%	2010	Std	Std
1	R10	1Meg	Resistor, Chip, 1Meg-Ohms, 1/16-W, 1%	603	Std	Std
2	J1-2	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
2	TP1 TP5	5010	Test Point, Red, Thru Hole	0.125 X .0125	5010	Keystone
3	TP2 TP6-7	5011	Test Point, Black, Thru Hole	0.125 X .0125	5011	Keystone
4	TP3-4 TP8-9	5012	Test Point, White, Thru Hole	0.125 X .0125	5012	Keystone
1	U1	TPS40200D	IC, Low Cost Sync Buck Controller	SO-8	TPS40200D	TI
1	Q1	SQ3427EEV	MOSFET, Automotive, Pch, -5.5A, -60V, 115 milliohm	SuperSOT-6	SQ3427EEV	Vishay
DNP"	= Do Not Pop	ulate				

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